

HEF4030B

Quad 2-input EXCLUSIVE-OR gate

Rev. 4 — 13 November 2013

Product data sheet

1. General description

The HEF4030B is a quad 2-input EXCLUSIVE-OR gate. The outputs are fully buffered for the highest noise immunity and pattern insensitivity to output impedance.

It operates over a recommended V_{DD} power supply range of 3 V to 15 V referenced to V_{SS} (usually ground). Unused inputs must be connected to V_{DD} , V_{SS} , or another input.

2. Features and benefits

- Fully static operation
- 5 V, 10 V, and 15 V parametric ratings
- Standardized symmetrical output characteristics
- Specified from $-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$
- Complies with JEDEC standard JESD 13-B
- Inputs and outputs are protected against electrostatic effects

3. Ordering information

Table 1. Ordering information

All types operate from $-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$

Type number	Package		Version
	Name	Description	
HEF4030BP	DIP14	plastic dual in-line package; 14 leads (300 mil)	SOT27-1
HEF4030BT	SO14	plastic small outline package; 14 leads; body width 3.9 mm	SOT108-1

4. Functional diagram

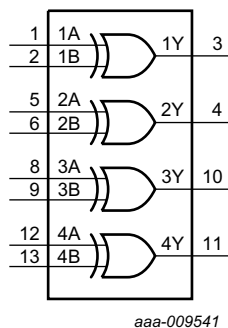


Fig 1. Functional diagram

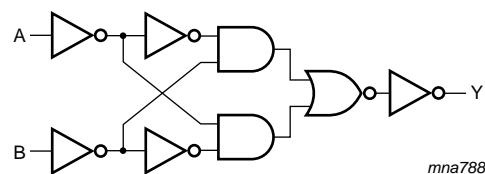


Fig 2. Logic diagram (one gate)



5. Pinning information

5.1 Pinning

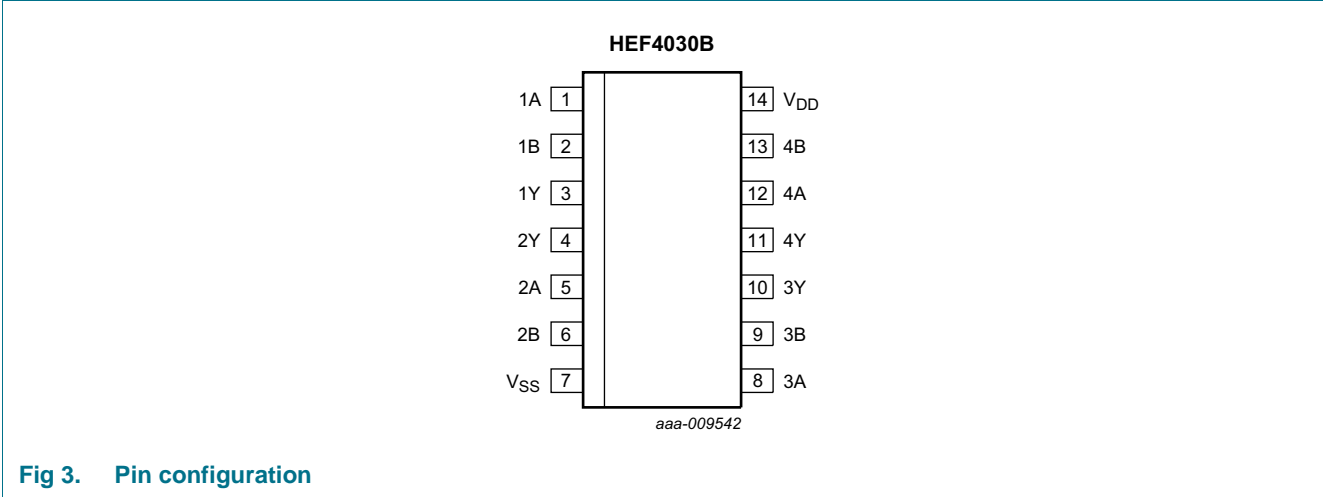


Fig 3. Pin configuration

5.2 Pin description

Table 2. Pin description

Symbol	Pin	Description
1A, 2A, 3A, 4A	1, 5, 8, 12	data input
1B, 2B, 3B, 4B	2, 6, 9, 13	data input
1Y, 2Y, 3Y, 4Y	3, 4, 10, 11	data output
V _{SS}	7	ground (0 V)
V _{DD}	14	supply voltage

6. Functional description

Table 3. Functional table^[1]

Input		Output
nA	nB	nY
L	L	L
L	H	H
H	L	H
H	H	L

[1] H = HIGH voltage level; L = LOW voltage level

7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to $V_{SS} = 0$ V (ground).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{DD}	supply voltage		-0.5	+18	V
I_{IK}	input clamping current	$V_I < -0.5$ V or $V_I > V_{DD} + 0.5$ V	-	± 10	mA
V_I	input voltage		-0.5	$V_{DD} + 0.5$	V
I_{OK}	output clamping current	$V_O < -0.5$ V or $V_O > V_{DD} + 0.5$ V	-	± 10	mA
I_{IO}	input/output current		-	± 10	mA
I_{DD}	supply current		-	50	mA
T_{stg}	storage temperature		-65	+150	°C
T_{amb}	ambient temperature		-40	+125	°C
P_{tot}	total power dissipation	$T_{amb} = -40$ °C to $+125$ °C			
		DIP14	[1] -	750	mW
		SO14	[2] -	500	mW
P	power dissipation	per output	-	100	mW

[1] For DIP14 packages: above $T_{amb} = 70$ °C, P_{tot} derates linearly with 12 mW/K.

[2] For SO14 packages: above $T_{amb} = 70$ °C, P_{tot} derates linearly with 8 mW/K.

8. Recommended operating conditions

Table 5. Recommended operating conditions

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{DD}	supply voltage		3	-	15	V
V_I	input voltage		0	-	V_{DD}	V
T_{amb}	ambient temperature	in free air	-40	-	+125	°C
$\Delta t/\Delta V$	input transition rise and fall rate	$V_{DD} = 5$ V	-	-	3.75	$\mu\text{s/V}$
		$V_{DD} = 10$ V	-	-	0.5	$\mu\text{s/V}$
		$V_{DD} = 15$ V	-	-	0.08	$\mu\text{s/V}$

9. Static characteristics

Table 6. Static characteristics

$V_{SS} = 0\text{ V}$; $V_I = V_{SS}$ or V_{DD} ; unless otherwise specified.

Symbol	Parameter	Conditions	V_{DD}	$T_{amb} = -40\text{ °C}$		$T_{amb} = +25\text{ °C}$		$T_{amb} = +85\text{ °C}$		$T_{amb} = +125\text{ °C}$		Unit
				Min	Max	Min	Max	Min	Max	Min	Max	
V_{IH}	HIGH-level input voltage	$ I_O < 1\text{ }\mu\text{A}$	5 V	3.5	-	3.5	-	3.5	-	3.5	-	V
			10 V	7.0	-	7.0	-	7.0	-	7.0	-	V
			15 V	11.0	-	11.0	-	11.0	-	11.0	-	V
V_{IL}	LOW-level input voltage	$ I_O < 1\text{ }\mu\text{A}$	5 V	-	1.5	-	1.5	-	1.5	-	1.5	V
			10 V	-	3.0	-	3.0	-	3.0	-	3.0	V
			15 V	-	4.0	-	4.0	-	4.0	-	4.0	V
V_{OH}	HIGH-level output voltage	$ I_O < 1\text{ }\mu\text{A}$	5 V	4.95	-	4.95	-	4.95	-	4.95	-	V
			10 V	9.95	-	9.95	-	9.95	-	9.95	-	V
			15 V	14.95	-	14.95	-	14.95	-	14.95	-	V
V_{OL}	LOW-level output voltage	$ I_O < 1\text{ }\mu\text{A}$	5 V	-	0.05	-	0.05	-	0.05	-	0.05	V
			10 V	-	0.05	-	0.05	-	0.05	-	0.05	V
			15 V	-	0.05	-	0.05	-	0.05	-	0.05	V
I_{OH}	HIGH-level output current	$V_O = 2.5\text{ V}$	5 V	-	-1.7	-	-1.4	-	-1.1	-	-1.1	mA
		$V_O = 4.6\text{ V}$	5 V	-	-0.64	-	-0.5	-	-0.36	-	-0.36	mA
		$V_O = 9.5\text{ V}$	10 V	-	-1.6	-	-1.3	-	-0.9	-	-0.9	mA
		$V_O = 13.5\text{ V}$	15 V	-	-4.2	-	-3.4	-	-2.4	-	-2.4	mA
I_{OL}	LOW-level output current	$V_O = 0.4\text{ V}$	5 V	0.64	-	0.5	-	0.36	-	0.36	-	mA
		$V_O = 0.5\text{ V}$	10 V	1.6	-	1.3	-	0.9	-	0.9	-	mA
		$V_O = 1.5\text{ V}$	15 V	4.2	-	3.4	-	2.4	-	2.4	-	mA
I_I	input leakage current		15 V	-	± 0.1	-	± 0.1	-	± 1.0	-	± 1.0	μA
I_{DD}	supply current	all valid input combinations; $I_O = 0\text{ A}$	5 V	-	0.25	-	0.25	-	7.5	-	7.5	μA
			10 V	-	0.5	-	0.5	-	15.0	-	15.0	μA
			15 V	-	1.0	-	1.0	-	30.0	-	30.0	μA
C_I	input capacitance			-	-	-	7.5	-	-	-	-	pF

10. Dynamic characteristics

Table 7. Dynamic characteristics

$T_{amb} = 25\text{ }^{\circ}\text{C}$; for waveforms see [Figure 4](#); for test circuit, see [Figure 5](#); unless otherwise specified.

Symbol	Parameter	Extrapolation formula ^[1]	V _{DD}	Min	Typ	Max	Unit
t _{PHL}	HIGH to LOW propagation delay	$57 + 0.55 \times C_L$	5 V	-	85	175	ns
		$24 + 0.23 \times C_L$	10 V	-	35	75	ns
		$22 + 0.16 \times C_L$	15 V	-	30	55	ns
t _{PLH}	LOW to HIGH propagation delay	$47 + 0.55 \times C_L$	5 V	-	75	150	ns
		$19 + 0.23 \times C_L$	10 V	-	30	65	ns
		$17 + 0.16 \times C_L$	15 V	-	25	50	ns
t _{THL}	HIGH to LOW output transition time	$10 + 1.00 \times C_L$	5 V	-	60	120	ns
		$9 + 0.42 \times C_L$	10 V	-	30	60	ns
		$6 + 0.28 \times C_L$	15 V	-	20	40	ns
t _{TLH}	LOW to HIGH output transition time	$10 + 1.00 \times C_L$	5 V	-	60	120	ns
		$9 + 0.42 \times C_L$	10 V	-	30	60	ns
		$6 + 0.28 \times C_L$	15 V	-	20	40	ns

[1] The typical value of the propagation delay and output transition time can be calculated with the extrapolation formula (C_L in pF).

Table 8. Dynamic power dissipation

$V_{SS} = 0\text{ V}$; $t_r = t_f \leq 20\text{ ns}$; $T_{amb} = 25\text{ }^{\circ}\text{C}$.

Symbol	Parameter	V _{DD}	Typical formula	Where
P _D	dynamic power dissipation	5 V	$P_D = 1100 \times f_i + \Sigma(f_o \times C_L) \times V_{DD}^2\text{ (}\mu\text{W)}$	f_i = input frequency in MHz;
		10 V	$P_D = 4900 \times f_i + \Sigma(f_o \times C_L) \times V_{DD}^2\text{ (}\mu\text{W)}$	f_o = output frequency in MHz;
		15 V	$P_D = 14400 \times f_i + \Sigma(f_o \times C_L) \times V_{DD}^2\text{ (}\mu\text{W)}$	C_L = output load capacitance in pF; $\Sigma(f_o \times C_L)$ = sum of the outputs; V_{DD} = supply voltage in V.

11. Waveforms

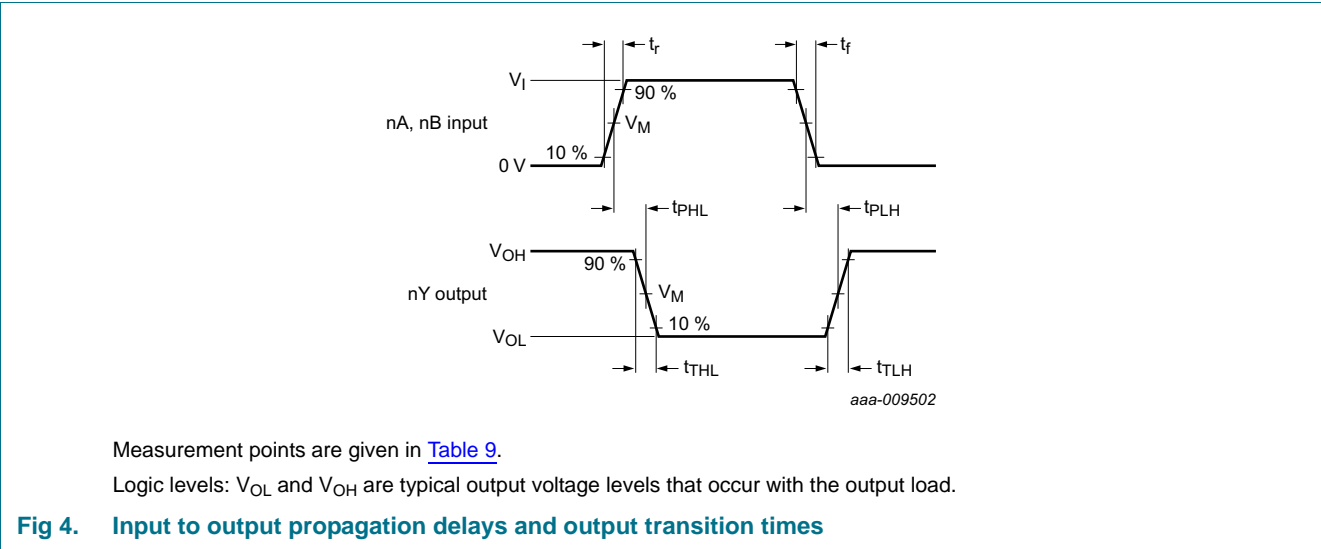


Table 9. Measurement points

Supply voltage	Input	Output
V_{DD}	V_M	V_M
5 V to 15 V	$0.5V_{DD}$	$0.5V_{DD}$

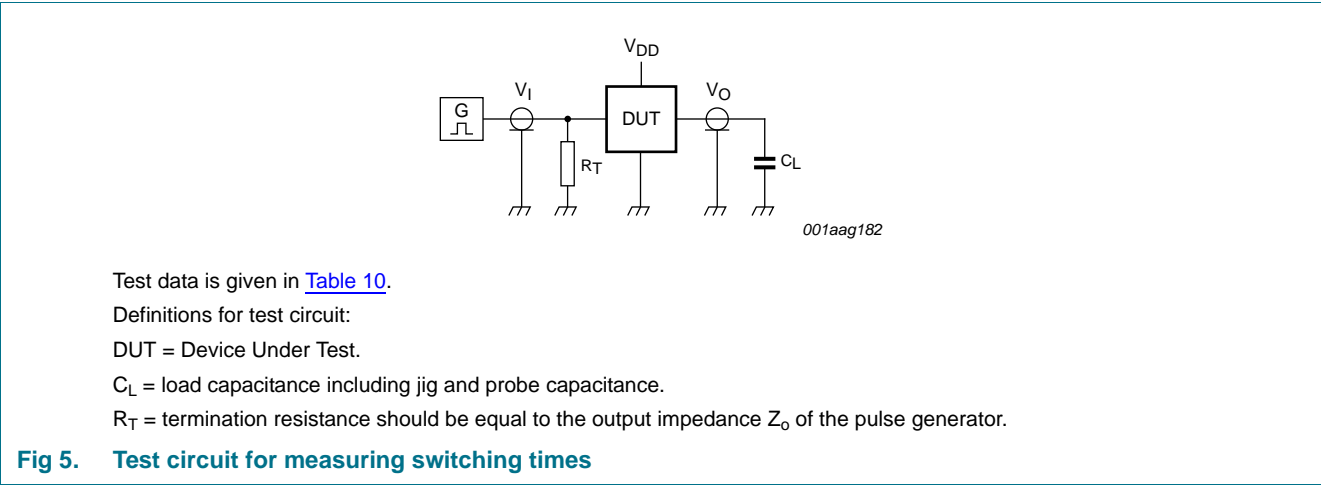


Table 10. Test data

Supply voltage	Input	Load
V_{DD}	V_I	C_L
5 V to 15 V	V_{SS} or V_{DD}	50 pF

12. Package outline

DIP14: plastic dual in-line package; 14 leads (300 mil)

SOT27-1

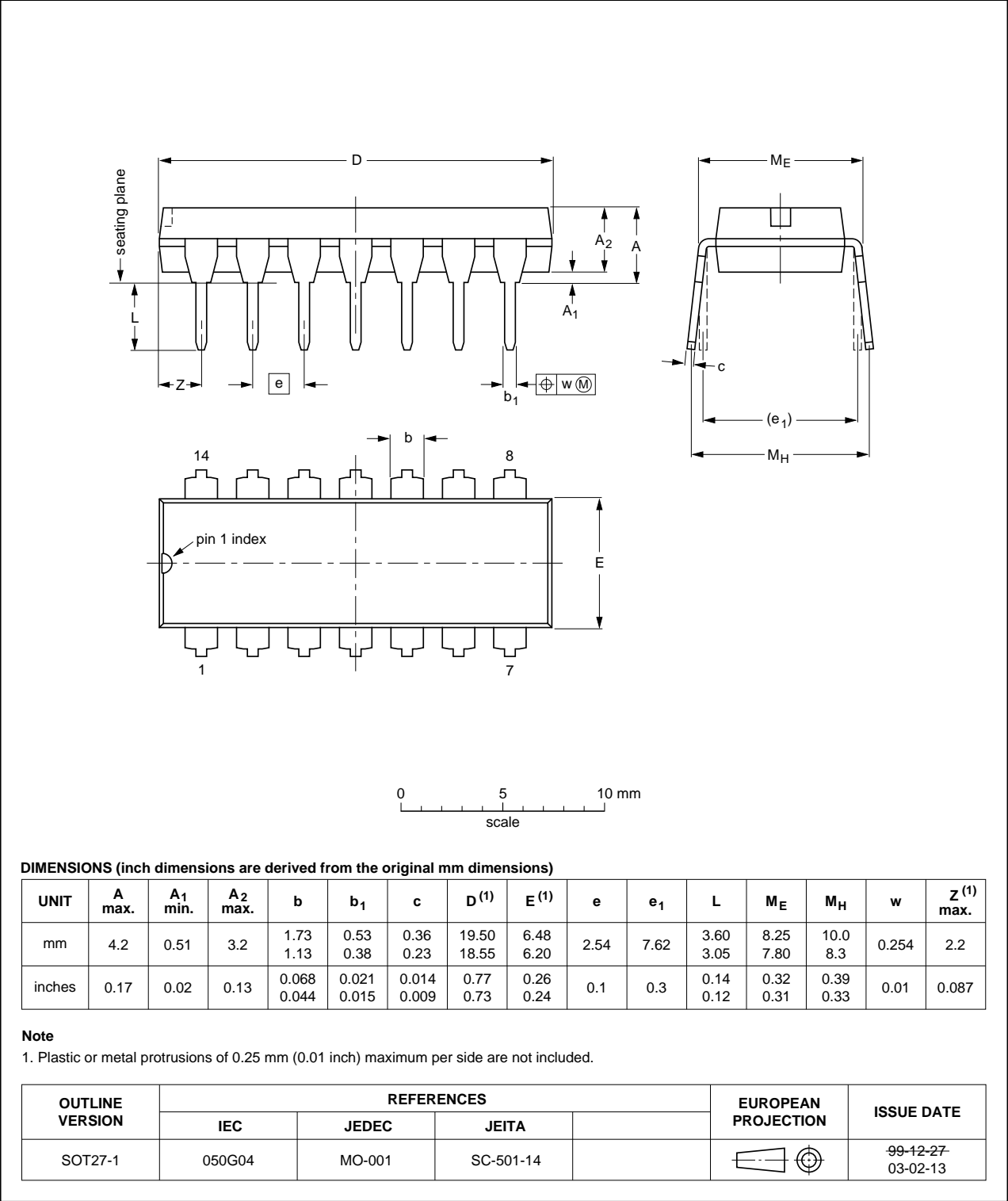


Fig 6. Package outline SOT27-1 (DIP14)

SO14: plastic small outline package; 14 leads; body width 3.9 mm

SOT108-1

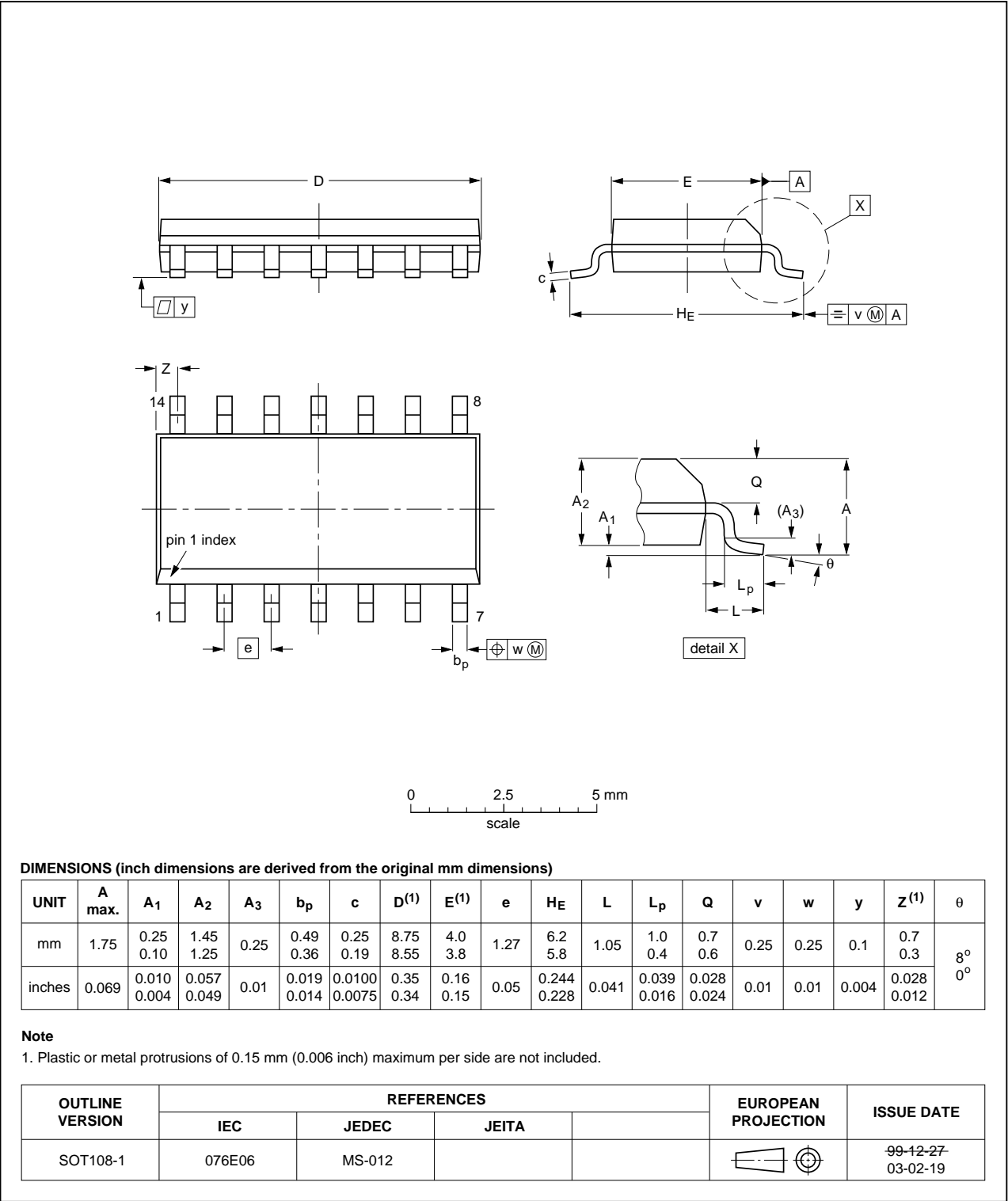


Fig 7. Package outline SOT108-1 (SO14)

13. Abbreviations

Table 11. Abbreviations

Acronym	Description
DUT	Device Under Test

14. Revision history

Table 12. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
HEF4030B v.4	20131113	Product data sheet	-	HEF4030B_CNV v.3
Modifications:	<ul style="list-style-type: none">• The format of this data sheet has been redesigned to comply with the new identity guidelines of NXP Semiconductors.• Legal texts have been adapted to the new company name where appropriate.• Changes in “General description” and “Features and benefits”.			
HEF4030B_CNV v.3	19950101	Product specification	-	-

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Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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